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Colleen J. Dew

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit 2827

In re application of : November 25, 2002  
Hormazdyar H. Dalal et al. : Examiner: John B. Vigushin  
Serial No. : 09/158,616 :  
Filed: September 22, 1998 : IBM Corporation  
 : Dept. 18G/Bldg, 300-482  
Title: A MULTI-LEVEL ELECTRONIC : 2070 Route 52  
PACKAGE AND METHOD FOR : Hopewell Junction, NY  
MAKING SAME : 12533-6531

Amendment

FAX RECEIVED

Commissioner for Patents and Trademarks  
Washington, D.C. 20231

NOV 25 2002

TECHNOLOGY CENTER 2800

Sir:

Kindly amend the claims as follows:

- 1 1. (4th amendment) A package for containing electronic components, the
- 2 package comprising:
- 3 a first circuitized card;
- 4 a second circuitized card;
- 5 an interposer interposed between the first and second circuitized cards,
- 6 the interposer having an opening, the opening in the interposer and the first and
- 7 second circuitized card forming a cavity for containing at least one electronic
- 8 component wherein the first circuitized card has a bottom surface and there is at
- 9 least one component mounted to the bottom surface, wherein the interposer, first
- 10 circuitized card, and second circuitized card are circuitized multi-layer organic
- 11 laminate cards, wherein the first circuitized card and interposed are electrically
- 12 and physically connected through a ball grid array and the interposer and the